HIGH-SPEED EDGE CARD SYSTEMS
0.60 mm, 0.80 mm and 1.00 mm PITCH

FEATURES & BENEFITS

- 56 Gbps PAM4 performance
- PCI Express® 3.0, 4.0 and 5.0
- Edge Rate® contacts optimized for signal integrity performance and cycle life
- Up to 200 positions available
- Vertical, right-angle, edge mount, pass-through orientations
- Power/signal combo, press-fit tails, rugged weld tabs, locks and latches
- Mating cable assemblies available

KEY SPECIFICATIONS

<table>
<thead>
<tr>
<th>SERIES</th>
<th>PITCH</th>
<th>TOTAL POSITIONS</th>
<th>INSULATOR MATERIAL</th>
<th>CONTACT MATERIAL</th>
<th>OPERATING TEMP RANGE</th>
<th>CURRENT RATING</th>
<th>VOLTAGE RATING</th>
<th>LEAD-FREE SOLDERABLE</th>
</tr>
</thead>
<tbody>
<tr>
<td>HSEC6</td>
<td>0.60 mm</td>
<td>56-168</td>
<td>Black LCP</td>
<td>Copper Alloy</td>
<td>-55 °C to +125 °C</td>
<td>0.8 A (12 pins)</td>
<td>300 VAC</td>
<td>Yes</td>
</tr>
<tr>
<td>HTEC8</td>
<td>0.80 mm</td>
<td>40-200</td>
<td>Black LCP</td>
<td>Copper Alloy</td>
<td>-55 °C to +125 °C</td>
<td>3.0 A (2 pins)</td>
<td>215 VAC</td>
<td>Yes</td>
</tr>
<tr>
<td>HSEC8</td>
<td>0.80 mm</td>
<td>18-200</td>
<td>Black LCP</td>
<td>BeCu</td>
<td>-55 °C to +125 °C</td>
<td>2.8 A (2 pins)</td>
<td>240 VAC</td>
<td>Yes</td>
</tr>
<tr>
<td>HSEC1</td>
<td>1.00 mm</td>
<td>20-140</td>
<td>Black LCP</td>
<td>Phosphor Bronze</td>
<td>-55 °C to +125 °C</td>
<td>2.2 A (2 pins)</td>
<td>215 VAC</td>
<td>Yes</td>
</tr>
</tbody>
</table>

Rugged tucked beam technology (HTEC8)
Differential pair for increased speed (HSEC8-DP)
Custom designs allow for misalignment in the X-Y axes (HSEC1)
HSEC8-DV
Card Mates:
(1.60 mm) .062” card
(2.36 mm) .093” card
HSC8
Cable Mates:
ECDP

OTHER SOLUTIONS
For complete edge card system with cards and sockets, visit samtec.com/RUB.
For a card to mate with an HSEC8 socket, visit samtec.com/HSC8